

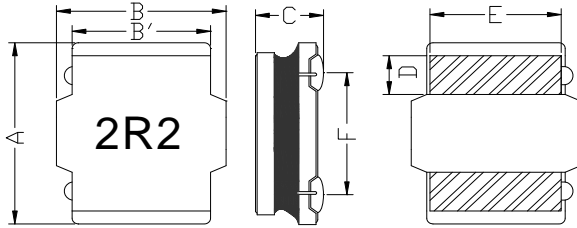
SMD Power Inductor YHC814N-Series

1. Features

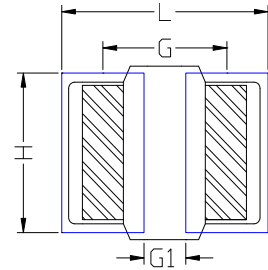
1. This specification applies Low Profile Power Inductors.
2. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
3. Operating temperature :-40~+125°C (Including self-temperature rise)



2. Dimensions



Recommended Land pattern

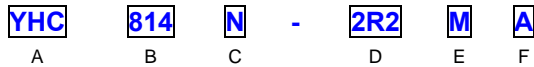


Series	Inductance	A(mm)	B(mm)	B'(mm)	C(mm)	D(mm)	E(mm)	F(mm)
YHC814N	<10uH	8.0±0.3	8.0±0.3	6.3±0.2	4.2Max	2.0±0.3	6.0±0.3	5.5±0.3
	≥10uH				3.7±0.3			

L(mm)	G(mm)	H(mm)	G1(mm)
8.5	5.5	6.3	2.5

Note: 1. The above PCB layout reference only.
2. Recommend solder paste thickness at 0.15mm and above.

3. Part Numbering



- A: Series
- B: Dimension A/B*C
- C: Type
- D: Inductance 2R2=2.20uH
- E: Inductance Tolerance M=±20%
- F: Code marking direction cannot decide polarity. Color: Black, unidirectional. magnetic shielding

4. Specification

Part Number	Inductance L0 (uH) @ 0 A	Tolerance				Rated current				DCR (mΩ) @25°C ±20%
						Temperature current I rms (A)		Saturation current I sat (A)		
		K	L	M	Y	Typ	Max	Typ	Max	
YHC814N-1R0□A	1.00	/	/	±20%	±30%	8.50	8.00	13.80	13.00	8.2
YHC814N-2R2□A	2.20	/	/	±20%	±30%	7.40	6.90	9.80	9.20	11.5
YHC814N-4R7□A	4.70	/	±15%	±20%	±30%	5.80	5.30	6.70	6.00	19.5
YHC814N-100□A	10.0	±10%	±15%	±20%	±30%	4.60	4.20	5.00	4.30	33.0
YHC814N-220□A	22.0	±10%	±15%	±20%	±30%	2.90	2.45	3.10	2.80	73.0
YHC814N-330□A	33.0	±10%	±15%	±20%	±30%	2.30	2.10	2.60	2.10	100
YHC814N-470□A	47.0	±10%	±15%	±20%	±30%	2.00	1.70	2.20	1.90	135

□:K±10%,L±15%,M±20%,Y±30%.

Note:

1. All test data referenced to 25°C ambient , Ls/Q:1MHz/1V.
2. Testing Instrument : HP4284A,CH11025,CH3302,CH1320 ,CH1320S LCR METER / Rdc:CH502BC MICRO OHMMETER.
3. Heat Rated Current (I rms) will cause the coil temperature rise approximately Δt of 40°C
4. Saturation Current (Isat) will cause L0 to drop approximately 30%
5. The part temperature (ambient + temp rise) should not exceed 125°C under worst case operating conditions.Circuit design,component,PCB trace size and thickness,airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
6. Special inquiries besides the above common used types can be met on your requirement.

5. Typical Performance Curves

